This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. Canceled

2. Canceled

3. Canceled

4. Canceled

Please add the following new claims:

--5. (New) A method for selecting a silica glass substrate, comprising polishing, cleaning, and drying silica glass slices, etching the silica glass slices to manifest potential defects on the entirety of the major surfaces of the slices so that the number of manifesting defects saturates the major surfaces, inspecting the entirety of the major surfaces of the slices for surface defects under a stereomicroscope, and selecting, as the substrate, those slices absent surface defects of a size of at least 0.3 μm in a direction parallel to the substrate's major surfaces.

6. (New) A method according to claim 5, wherein the etching of the slice removes a thickness of 0.2 - 0.5 μm.

7. (New) A method according to claim 5, wherein the cleaning, etching or both comprises providing a reactive reagent.

8. (New) A method according to claim 7, wherein the etching comprises

providing a reactive reagent, which comprises a fluoride ion-containing compound.

9. (New) A method according to claim 7, wherein the etching comprises providing a reactive reagent, which comprises a concentrated, diluted, or buffered hydrofluoric acid.

10. (New) A method according to claim 7, wherein the etching comprises providing a reactive reagent, which comprises a solution, comprising a surfactant and a reaction control agent.

11. (New) A method according to claim 7, wherein the reactive reagent is an acidic or an alkaline chemical.

12. (New) A method according to claim 11, wherein the reactive reagent is hydrofluoric acid, a buffered hydrofluoric acid, ammonium fluoride, ammonium monohydrogen difluoride, borofluoric acid, sulfuric acid, nitric acid, hydrochloric acid, acetic acid, citric acid, malic acid, oxalic acid, or perchloric acid.

13. (New) A method according to claim 11, wherein the reactive reagent is sodium hydroxide, potassium hydroxide, calcium hydroxide, ammonia or an amine.

14. (New) A method according to claim 7, wherein the reactive reagent is carbon tetrafluoride, methane trifluoride, sulfur hexafluoride or hydrogen fluoride.

15. (New) A method according to claim 5, wherein the etching of the slice removes a thickness of 0.3 μm.

16. (New) A method of screening a silica glass substrate for incorporation in an electronic, a microelectronic, or a microanalytic device, comprising selecting an etched silica

glass substrate absent defects of at least 0.3 μm in a direction parallel to the substrate's major surfaces by inspecting the major surfaces for such defects with a stereomicroscope.

17. (New) A method of screening silica glass substrates for incorporation in an electronic, a microelectronic, or a microanalytic device, comprising a step for selecting etched silica glass substrates absent defects of at least 0.3 μm in a direction parallel to the substrates' major surfaces by inspecting the major surfaces for such defects with a stereomicroscope.

18. (New) A method according to claim 5, wherein each of the slices have a diameter of six inches.--